

CHIP PACKAGE CAPABLE OF REDUCING MOISTURE PENETRATION

ABSTRACT OF THE DISCLOSURE

5        A semiconductor chip package is formed to be capable of reducing moisture erosion by configuring the bonding finger, the plating-conduction-line, and the trace on the chip carrier therein in such a way that the length of path for moisture to penetrate and to reach the bonding finger through a plating-conduction-line is significantly longer

10      than those implemented in a conventional chip package.

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